Automotive Dual N-Channel 20 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	20
$R_{DS(on)}$ (Ω) at V_{GS} = 4.5 V	0.415
$R_{DS(on)}$ (Ω) at V_{GS} = 2.5 V	0.600
I_D (A)	0.78
Configuration	Dual
Package	SC-70

FEATURES

- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- AEC-Q101 qualified [c]
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

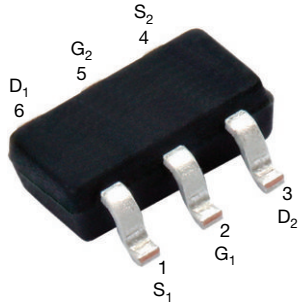
AUTOMOTIVE GRADE

Pb-free

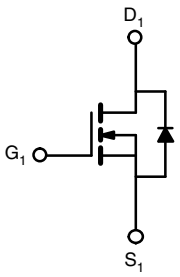
RoHS COMPLIANT

HALOGEN FREE

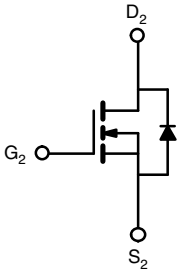
SOT-363
SC-70 Dual (6 leads)



Top View



N-Channel MOSFET



N-Channel MOSFET

Marking Code: 9P

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)				
PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 12	
Continuous Drain Current	T_C = 25 °C	I_D	0.78	A
	T_C = 125 °C		0.45	
Continuous Source Current (Diode Conduction)		I_S	0.54	
Pulsed Drain Current [a]		I_{DM}	3	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	3.5	
Single Pulse Avalanche Energy		E_{AS}	0.6	mJ
Maximum Power Dissipation [a]	T_C = 25 °C	P_D	0.43	W
	T_C = 125 °C		0.14	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Junction-to-Ambient	PCB Mount [b]	R_{thJA}	460	°C/W
Junction-to-Foot (Drain)		R_{thJF}	350	

Notes

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. When mounted on 1" square PCB (FR4 material).
c. Parametric verification ongoing.

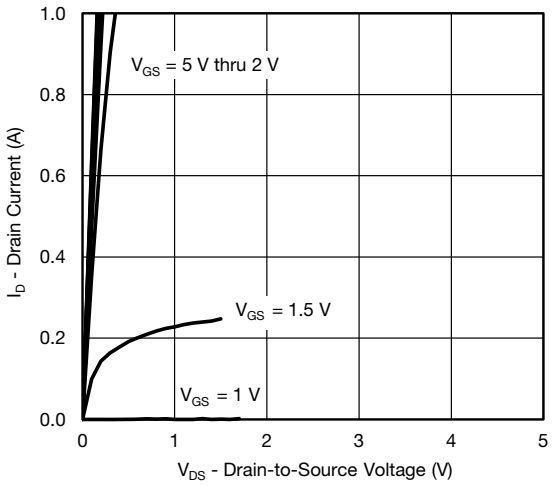
SPECIFICATIONS (T_C = 25 °C, unless otherwise noted)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0, I_D = 250 µA		20	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		0.6	1.0	1.5	
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 12 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V	V_{DS} = 20 V	-	-	1	µA
		V_{GS} = 0 V	V_{DS} = 20 V, T_J = 125 °C	-	-	50	
		V_{GS} = 0 V	V_{DS} = 20 V, T_J = 175 °C	-	-	150	
On-State Drain Current [a]	$I_{D(on)}$	V_{GS} = 4.5 V	V_{DS} ≥ 5 V	0.8	-	-	A
Drain-Source On-State Resistance [a]	$R_{DS(on)}$	V_{GS} = 4.5 V	I_D = 0.66 A	-	0.200	0.415	Ω
		V_{GS} = 4.5 V	I_D = 0.66 A, T_J = 125 °C	-	-	0.594	
		V_{GS} = 4.5 V	I_D = 0.66 A, T_J = 175 °C	-	-	0.698	
		V_{GS} = 2.5 V	I_D = 0.4 A	-	0.250	0.600	
Forward Transconductance [b]	g_{fs}	V_{DS} = 10 V, I_D = 1 A		-	1.1	-	S
Dynamic [b]							
Input Capacitance	C_{iss}	V_{GS} = 0 V	V_{DS} = 10 V, f = 1 MHz	-	50	75	pF
Output Capacitance	C_{oss}			-	21	28	
Reverse Transfer Capacitance	C_{rss}			-	9	15	
Total Gate Charge [c]	Q_g	V_{GS} = 4.5 V	V_{DS} = 10 V, I_D = 1.2 A	-	0.7	1.2	nC
Gate-Source Charge [c]	Q_{gs}			-	0.1	-	
Gate-Drain Charge [c]	Q_{gd}			-	0.1	-	
Gate Resistance	R_g	f = 1 MHz		4.5	9.1	13.7	Ω
Turn-On Delay Time [c]	$t_{d(on)}$	V_{DD} = 10 V, R_L = 20 Ω I_D ≅ 0.5 A, V_{GEN} = 4.5 V, R_g = 1 Ω		-	10	15	ns
Rise Time [c]	t_r			-	22	30	
Turn-Off Delay Time [c]	$t_{d(off)}$			-	20	28	
Fall Time [c]	t_f			-	18	25	
Source-Drain Diode Ratings and Characteristics [b]							
Pulsed Current [a]	I_{SM}			-	-	3	A
Forward Voltage	V_{SD}	I_F = 0.5 A, V_{GS} = 0		-	0.85	1.2	V

Notes

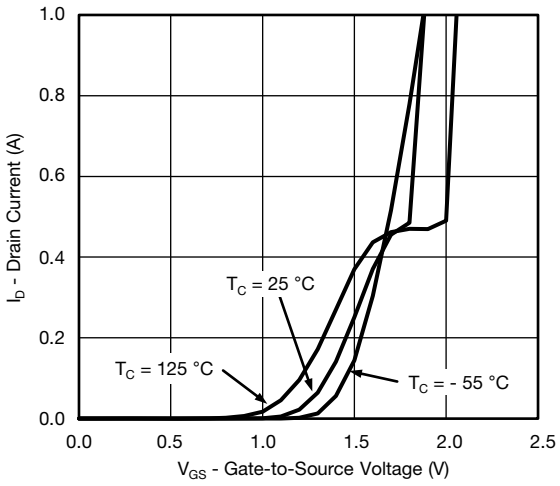
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

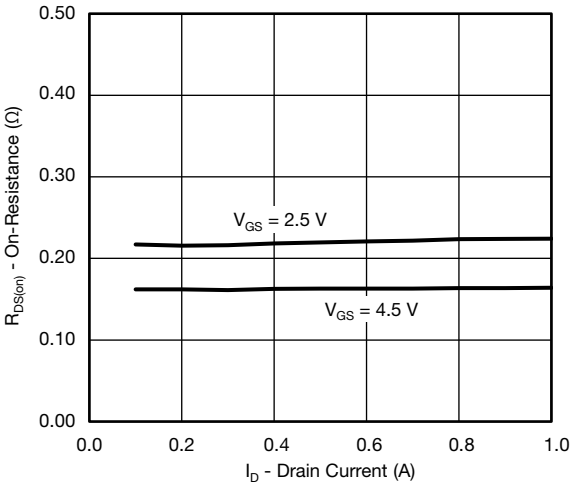
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



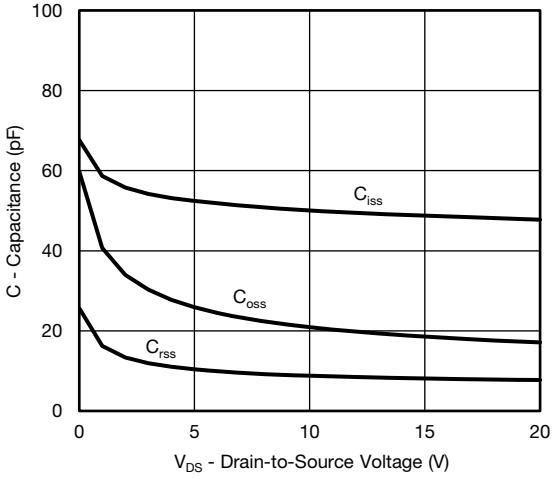
Output Characteristics



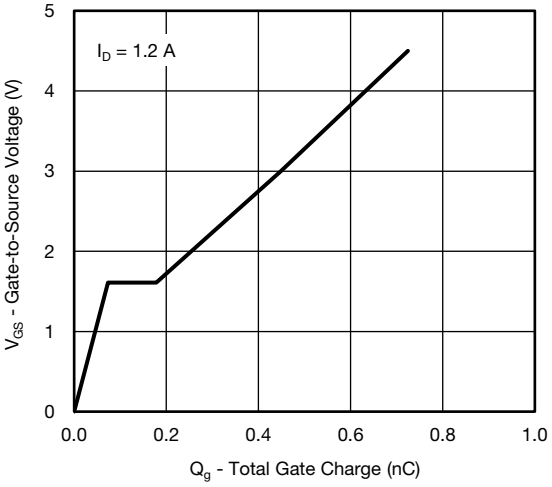
Transfer Characteristics



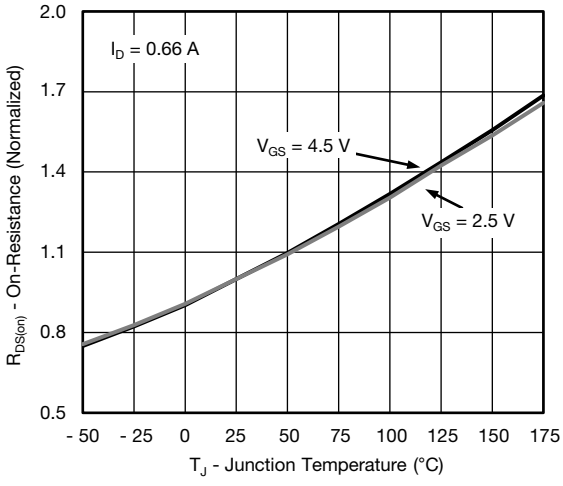
On-Resistance vs. Drain Current



Capacitance

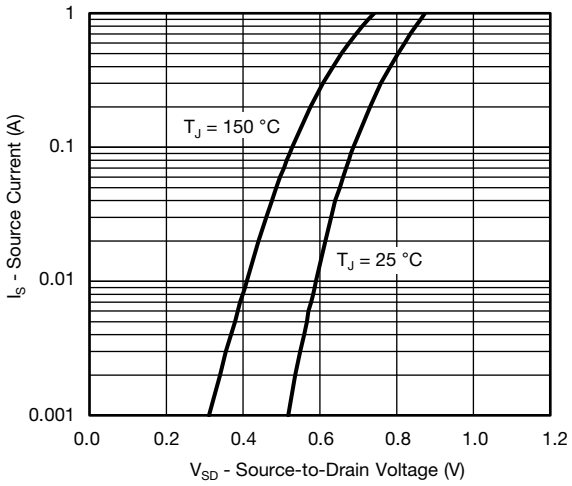


Gate Charge

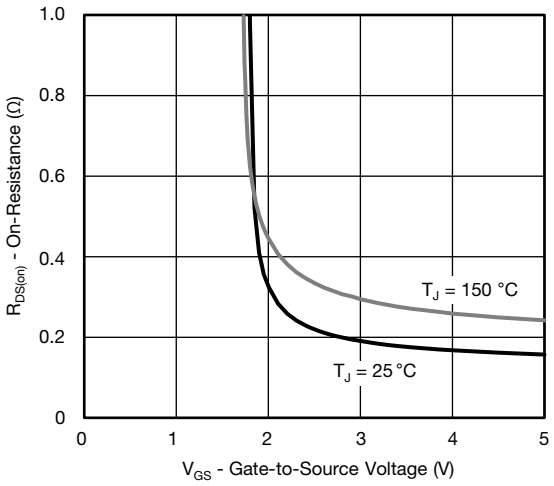


On-Resistance vs. Junction Temperature

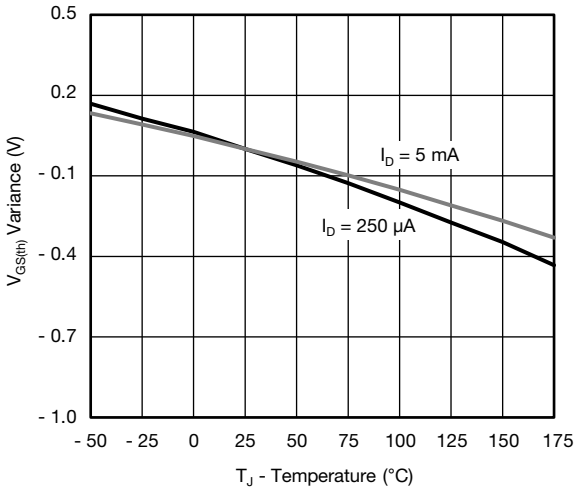
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



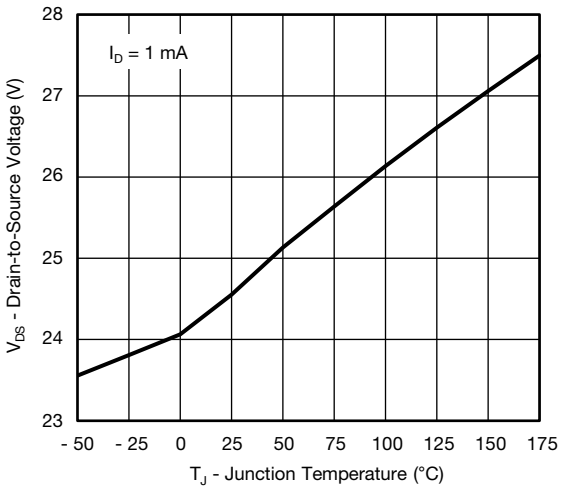
Source Drain Diode Forward Voltage



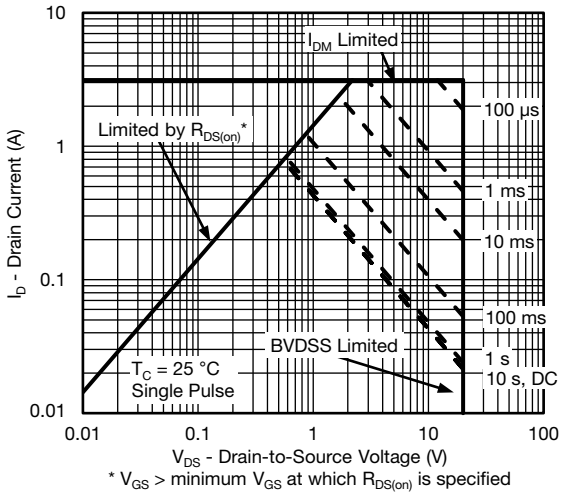
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

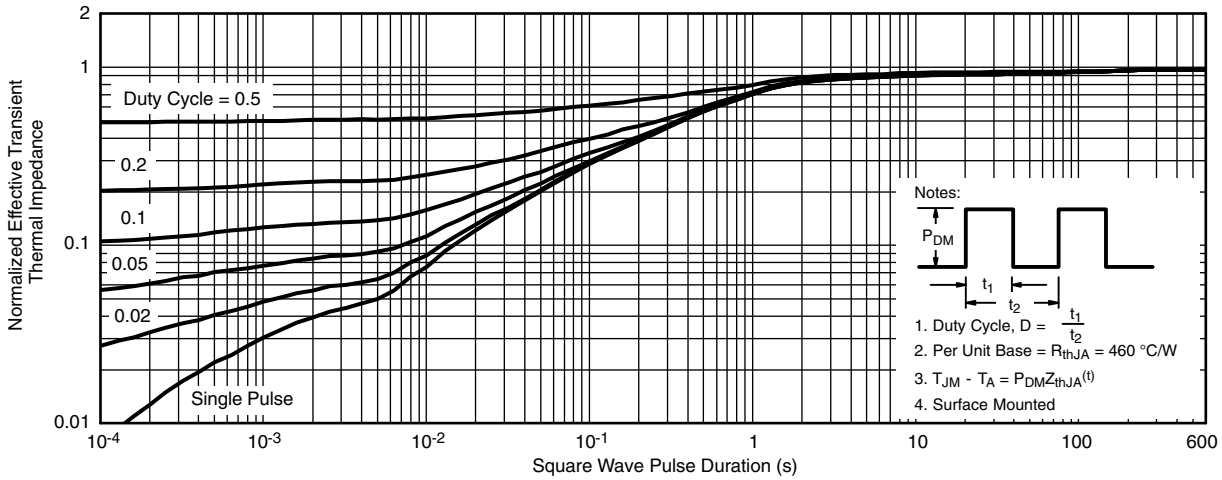


Drain Source Breakdown vs. Junction Temperature

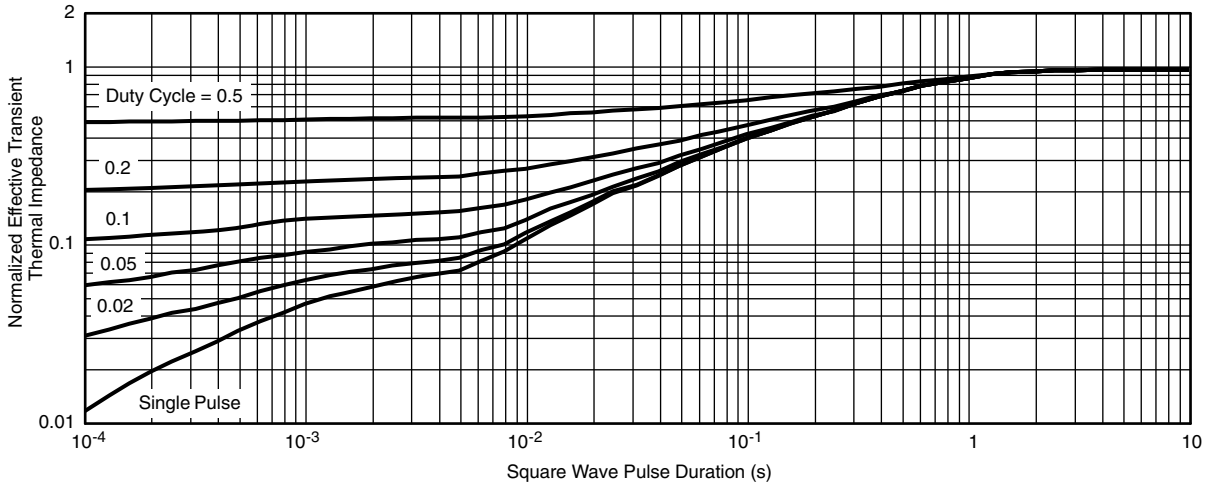


Safe Operating Area

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

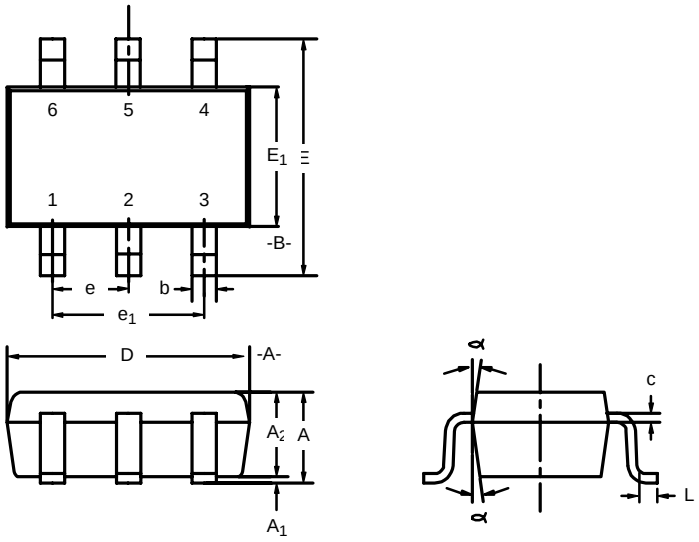
Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

  are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62977.

SC-70: 6-LEADS



Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.90	–	1.10	0.035	–	0.043
A_1	–	–	0.10	–	–	0.004
A_2	0.80	–	1.00	0.031	–	0.039
b	0.15	–	0.30	0.006	–	0.012
c	0.10	–	0.25	0.004	–	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.80	2.10	2.40	0.071	0.083	0.094
E_1	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65BSC			0.026BSC		
e_1	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
α	7°Nom			7°Nom		

ECN: S-03946—Rev. B, 09-Jul-01
DWG: 5550

Dual-Channel LITTLE FOOT® SC-70 6-Pin MOSFET Recommended Pad Pattern and Thermal Performance

INTRODUCTION

This technical note discusses the pin-outs, package outlines, pad patterns, evaluation board layout, and thermal performance for dual-channel LITTLE FOOT power MOSFETs in the SC-70 package. These new Vishay Siliconix devices are intended for small-signal applications where a miniaturized package is needed and low levels of current (around 250 mA) need to be switched, either directly or by using a level shift configuration. Vishay provides these devices with a range of on-resistance specifications in 6-pin versions. The new 6-pin SC-70 package enables improved on-resistance values and enhanced thermal performance.

PIN-OUT

Figure 1 shows the pin-out description and Pin 1 identification for the dual-channel SC-70 device in the 6-pin configuration.

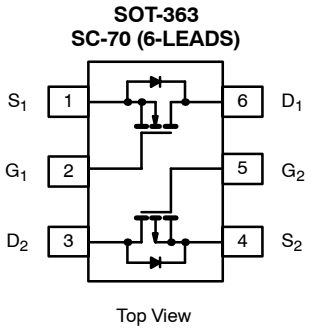


FIGURE 1.

For package dimensions see outline drawing SC-70 (6-Leads) (http://www.vishay.com/doc?71154)

BASIC PAD PATTERNS

See Application Note 826, *Recommended Minimum Pad Patterns With Outline Drawing Access for Vishay Siliconix MOSFETs*, (http://www.vishay.com/doc?72286) for the 6-pin SC-70. This basic pad pattern is sufficient for the low-power applications for which this package is intended. For the 6-pin device, increasing the pad patterns yields a reduction in thermal resistance on the order of 20% when using a 1-inch square with full copper on both sides of the printed circuit board (PCB).

EVALUATION BOARDS FOR THE DUAL SC70-6

The 6-pin SC-70 evaluation board (EVB) measures 0.6 inches by 0.5 inches. The copper pad traces are the same as described in the previous section, *Basic Pad Patterns*. The board allows interrogation from the outer pins to 6-pin DIP connections permitting test sockets to be used in evaluation testing.

The thermal performance of the dual SC-70 has been measured on the EVB with the results shown below. The minimum recommended footprint on the evaluation board was compared with the industry standard 1-inch square FR4 PCB with copper on both sides of the board.

THERMAL PERFORMANCE

Junction-to-Foot Thermal Resistance (the Package Performance)

Thermal performance for the dual SC-70 6-pin package measured as junction-to-foot thermal resistance is 300°C/W typical, 350°C/W maximum. The “foot” is the drain lead of the device as it connects with the body. Note that these numbers are somewhat higher than other LITTLE FOOT devices due to the limited thermal performance of the Alloy 42 lead-frame compared with a standard copper lead-frame.

Junction-to-Ambient Thermal Resistance (dependent on PCB size)

The typical $R\theta_{JA}$ for the dual 6-pin SC-70 is 400°C/W steady state. Maximum ratings are 460°C/W for the dual. All figures based on the 1-inch square FR4 test board. The following example shows how the thermal resistance impacts power dissipation for the dual 6-pin SC-70 package at two different ambient temperatures.

SC-70 (6-PIN)	
Room Ambient 25 °C	**Elevated Ambient 60 °C**
$P_D = \frac{T_{J(max)} - T_A}{R\theta_{JA}}$	$P_D = \frac{T_{J(max)} - T_A}{R\theta_{JA}}$
$P_D = \frac{150°C - 25°C}{400°C/W}$	$P_D = \frac{150°C - 60°C}{400°C/W}$
P_D = 312 mW	P_D = 225 mW

NOTE: Although they are intended for low-power applications, devices in the 6-pin SC-70 will handle power dissipation in excess of 0.2 W.

Testing

To aid comparison further, Figure 2 illustrates the dual-channel SC-70 thermal performance on two different board sizes and two different pad patterns. The results display the thermal performance out to steady state. The measured steady state values of $R\theta_{JA}$ for the dual 6-pin SC-70 are as follows:

LITTLE FOOT SC-70 (6-PIN)	
1) Minimum recommended pad pattern (see Figure 2) on the EVB of 0.5 inches x 0.6 inches.	518°C/W
2) Industry standard 1" square PCB with maximum copper both sides.	413°C/W

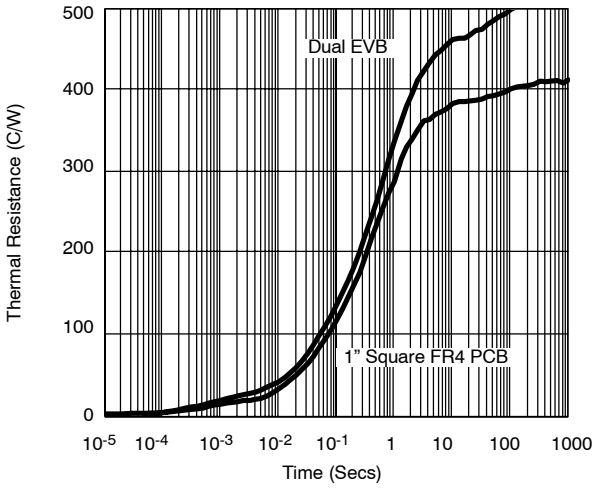


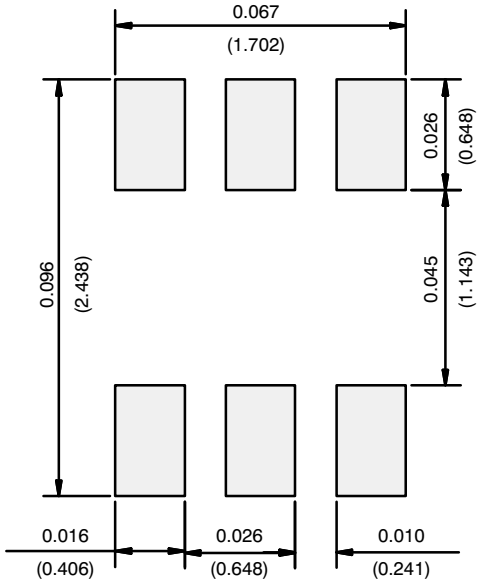
FIGURE 2. Comparison of Dual SC70-6 on EVB and 1" Square FR4 PCB.

The results show that if the board area can be increased and maximum copper traces are added, the thermal resistance reduction is limited to 20%. This fact confirms that the power dissipation is restricted with the package size and the Alloy 42 leadframe.

ASSOCIATED DOCUMENT

Single-Channel LITTLE FOOT SC-70 6-Pin MOSFET Copper Leadframe Version, REcommended Pad Pattern and Thermal Performance, AN815, (http://www.vishay.com/doc?71334).

RECOMMENDED MINIMUM PADS FOR SC-70: 6-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

Return to Index

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